

WHAT IS CLAIMED IS:

1. A semiconductor laser package comprising:  
an island member formed of metal, including a base plane and a  
block member protruding in a direction substantially perpendicular to said  
base plane,  
5 a lead,  
a resin member molded integrally with said island member and said  
lead so as to fix a relative position relationship between said island member  
and said lead,  
10 a laser chip fixed at said block member so as to enable emission of a  
laser beam in a direction substantially perpendicular to said base plane, and  
a light receiving unit directly fixed at said resin member.
2. The semiconductor laser package according to claim 1, wherein  
said resin member has a light receiving unit attaching plane substantially  
parallel to said base plane, and said light receiving unit is mounted at said  
light receiving unit attaching plane.
3. The semiconductor laser package according to claim 1, wherein a  
heat radiator is fixed at said block unit, and said laser chip is fixed to said  
block unit so as to form contact with said heat radiator.
4. The semiconductor laser package according to claim 3, wherein  
said heat radiator comprises light receiving means.
5. The semiconductor laser package according to claim 1, wherein a  
hologram element is arranged located on an optical path of a laser beam  
emitted from said laser chip.
6. The semiconductor laser package according to claim 1,  
comprising a cover to enclose said laser chip and said light receiving unit.

7. A fabrication method of a semiconductor laser package comprising:

5 a resin member molding step of molding an island member formed of metal, including a base plane and a block member protruding substantially in a direction of a normal line to said base plane, and a lead integrally with resin so as to fix a relative position relationship between said island member and lead,

10 a laser chip attaching step of fixing a laser chip at said block member so as to enable emission of a laser beam in a direction of the normal line of said base plane, and

a light receiving unit attaching step of fixing a light receiving unit at said resin member.

8. The fabrication method of a semiconductor laser package according to claim 7, wherein said resin member molding step includes the step of arranging said island member and said lead in a same resin molding die and effect resin molding.

9. The fabrication method of a semiconductor laser package according to claim 7, further comprising an island member formation step of forming said island member by cold forging.

10. The fabrication method of a semiconductor laser package according to claim 7, wherein said lead is formed by shaping through press-working, and applying a bending process.

5 11. An optical pick up apparatus comprising a semiconductor laser package defined in claim 1, and a lens, wherein said lens is fixed so that a focal point substantially matches a light emitting point of said laser chip.